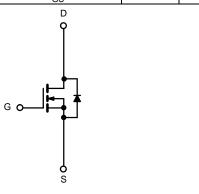


AUFU8405-VB Datasheet N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, c}	Q _g (Typ.)			
40	0.0016 at V _{GS} = 10 V	120	120 nC			
40	0.0020 at $V_{GS} = 4.5 \text{ V}$	100	120110			



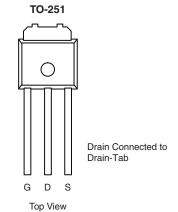
FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested

RoHS

APPLICATIONS

- Synchronous Rectification
- Power Supplies



N-Channel	MOSEFT

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V	3semiv@6688	40	V	
Gate-Source Voltage		V _{GS}	± 25	V	
	T _C = 25 °C		120 ^{a, c}	A	
Continuous Drain Current (T. – 175 °C)	T _C = 70 °C] , [96 ^c		
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	- I _D	29 ^b		
	T _A = 70 °C		23 ^b		
Pulsed Drain Current		I _{DM}	250		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	96		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	320	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	la la	120 ^{a, c}	А	
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	2.6 ^b	A	
	T _C = 25 °C		312 ^a	W	
Maximum Daylar Dissipation	T _C = 70 °C] _B	200		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.13 ^b		
	T _A = 70 °C]	2.0 ^b		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R_{thJC}	0.33	0.4	C/VV		

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. Calculated based on maximum junction temperature. Package limitation current is 120 $\,\mathrm{A.}$



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		41		mV/°(
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1D = 200 μΛ		- 8		mv/·C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zone Onto Vellana Buria Oceani	lana	V _{DS} = 40 V, V _{GS} = 0 V			1	^	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10 µA		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
David Course Co. Otata Basista and	D	V _{GS} = 10 V, I _D = 30 A		0.0016		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 20 A		0.0020			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		180		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			9000			
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		650		pF	
Reverse Transfer Capacitance	C _{rss}			450			
Total Gate Charge	Q_{g}			120	180	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		30			
Gate-Drain Charge	Q _{gd}			16			
Gate Resistance	R_{g}	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		11	17	- - -	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		77	115		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			102	155	ns	
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		180	270		
Fall Time	t _f			60	90		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			110	^	
Pulse Diode Forward Current ^a	I _{SM}				200	Α	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 00 A di/dt 400 A/v- T 05 00		70	105	nC	
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		30		1	
Reverse Recovery Rise Time	t _b	_		20		ns	

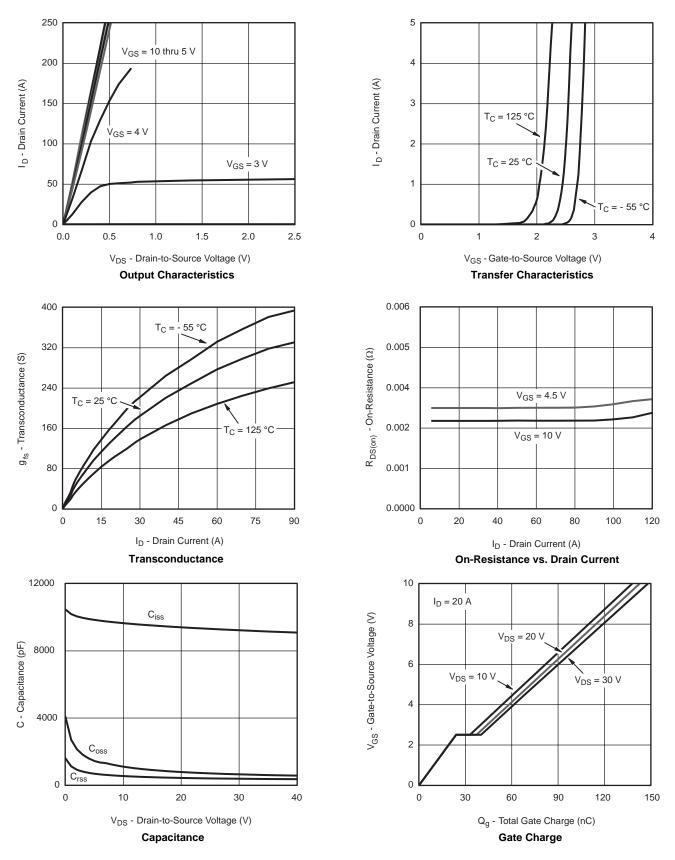
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

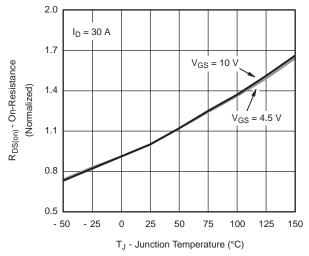


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

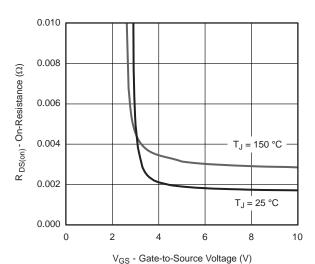




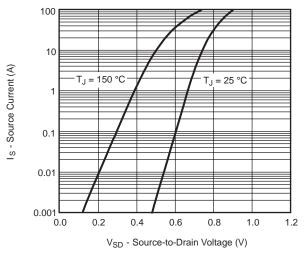
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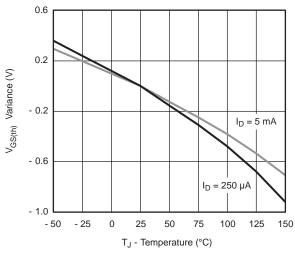
On-Resistance vs. Junction Temperature



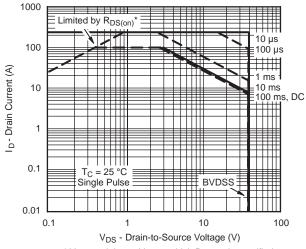
On-Resistance vs. Gate-to-Source Voltage



Forward Diode Voltage vs. Temperature



Threshold Voltage

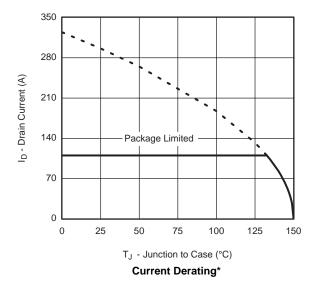


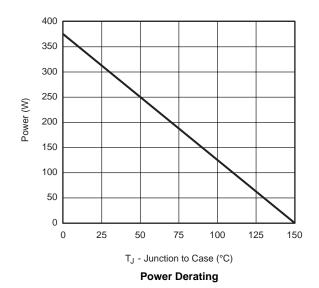
 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

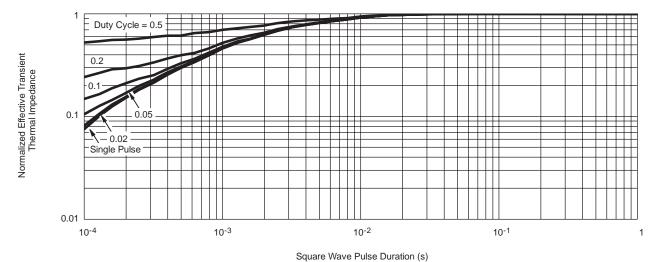


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





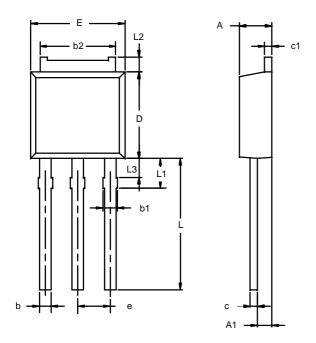
* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA



Note: Dimension L3 is for reference only.

	MILLIMETERS		INC	HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
с1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
Е	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090 BSC	
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060



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